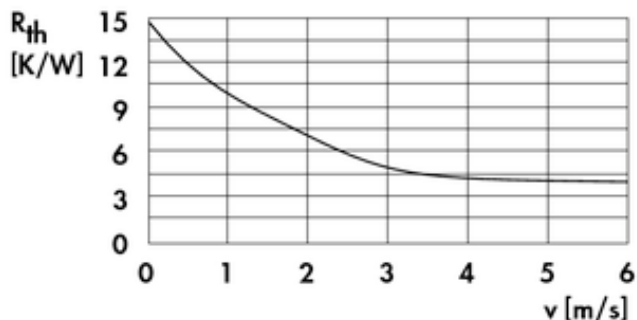
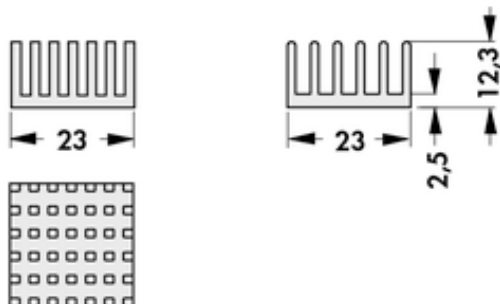
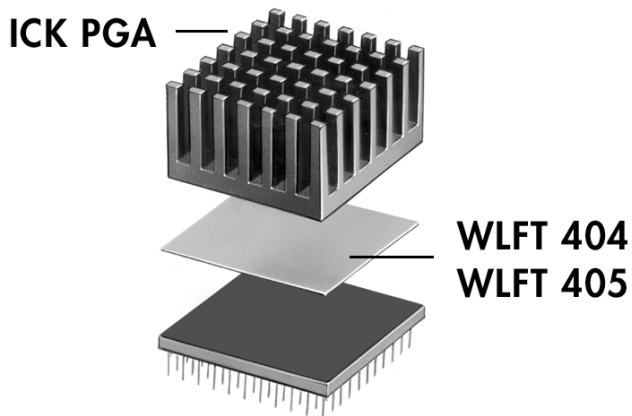


Heatsinks for PGA / **ICK PGA 8 x 8 x 12**



23 x 23 x 12,3 mm, for IC design PGA and others

Parameters of article **ICK PGA 8 x 8 x 12**

R_{th} [K/W]	14.8
dissipation loss [W]	8.1
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
width [mm]	23
height [mm]	12.3
plate thickness [mm]	2.5
length on stock [mm]	23
surface treatment	black anodised

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 23 x 23**

Thermally conductive foil both sides adhesive / **WLFT 405 23 x 23**